

WNM3049

Single N-Channel, 30V, 5.2A, Power MOSFET

[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

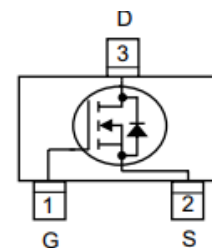
V_{DS} (V)	Typical $R_{DS(on)}$ (m Ω)
30	24 @ $V_{GS} = 10.0V$
	25 @ $V_{GS} = 4.5V$
	27 @ $V_{GS} = 3.1V$
	29 @ $V_{GS} = 2.5V$



SOT-23-3L

Descriptions

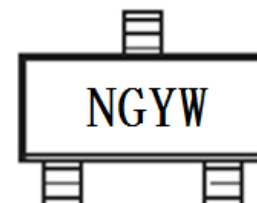
The WNM3049 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM3049 is Pb-free.



Pin configuration (Top view)

Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package SOT-23-3L



NG = Device Code
 Y = Year
 W = Week(A~z)

Applications

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

Marking

Order information

Device	Package	Shipping
WNM3049-3/TR	SOT-23-3L	3000/Tape&Reel

Absolute Maximum ratings

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 10	
Continuous Drain Current	I_D	$T_A=25^{\circ}\text{C}$ 5.2	A
		$T_A=70^{\circ}\text{C}$ 4.2	
Pulsed Drain Current ^c	I_{DM}	30	
Maximum Power Dissipation ^b	P_D	$T_A=25^{\circ}\text{C}$ 1.3	W
		$T_A=70^{\circ}\text{C}$ 0.9	
Operating Junction Temperature	T_J	-55 to 150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}\text{C}$

Thermal resistance ratings

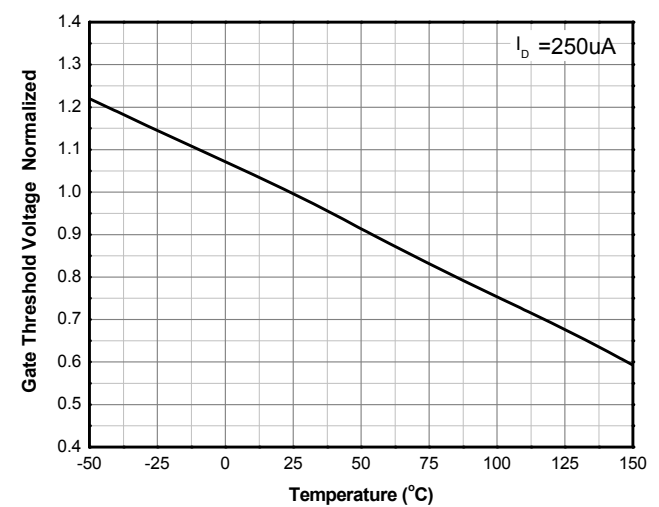
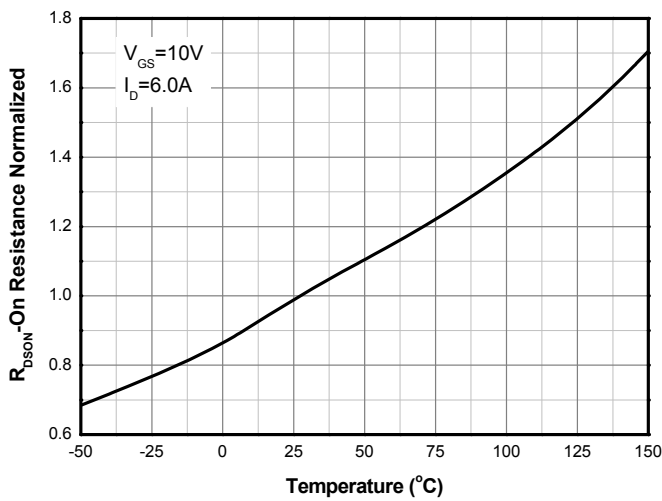
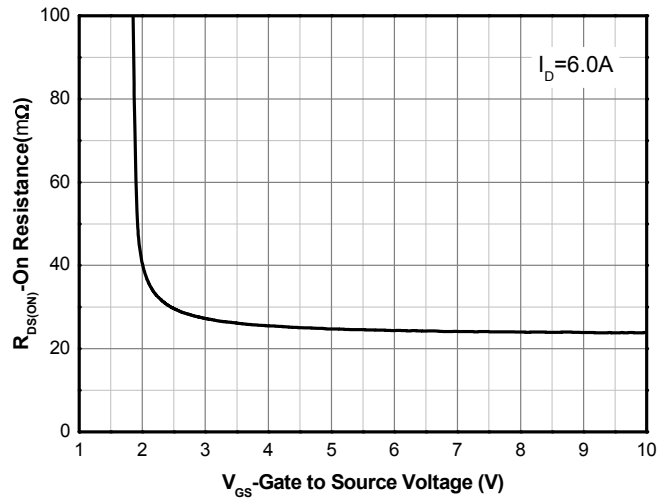
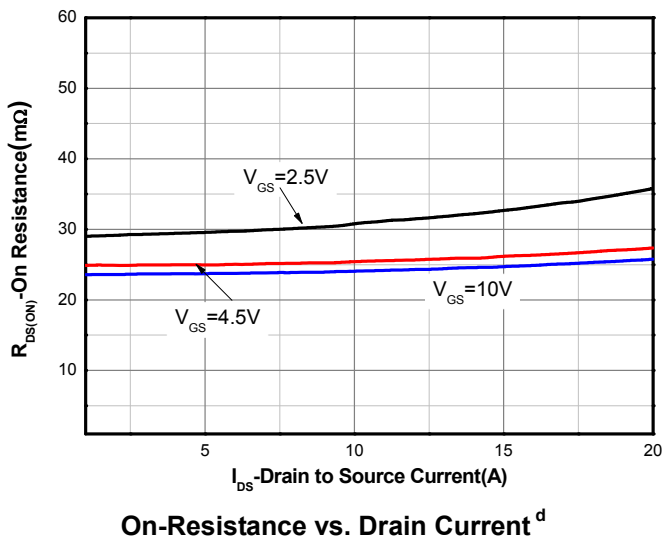
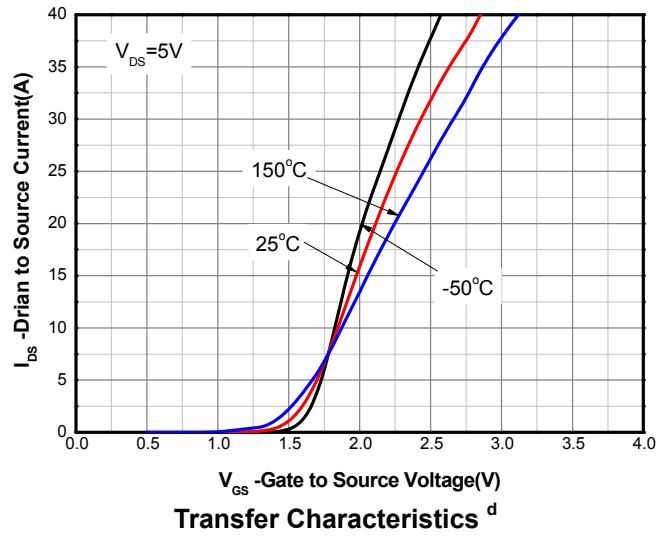
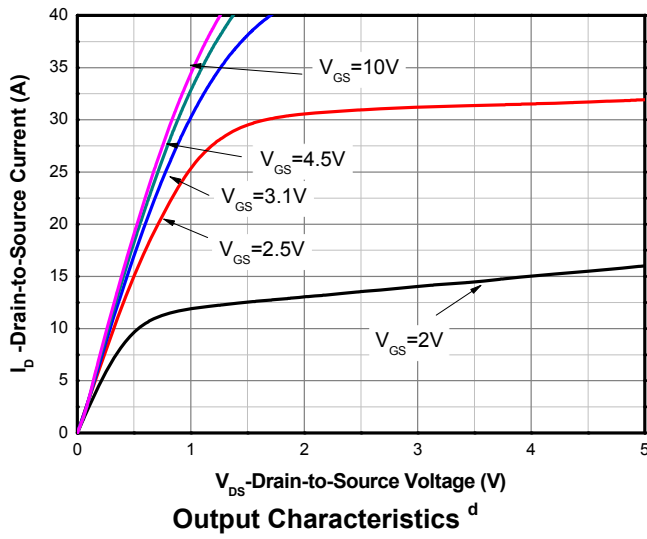
Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$R_{\theta JA}$	$t \leq 10\text{ s}$ 69	93	$^{\circ}\text{C/W}$
		Steady State 91	114	
Junction-to-Lead Thermal Resistance	$R_{\theta JL}$	46	58	

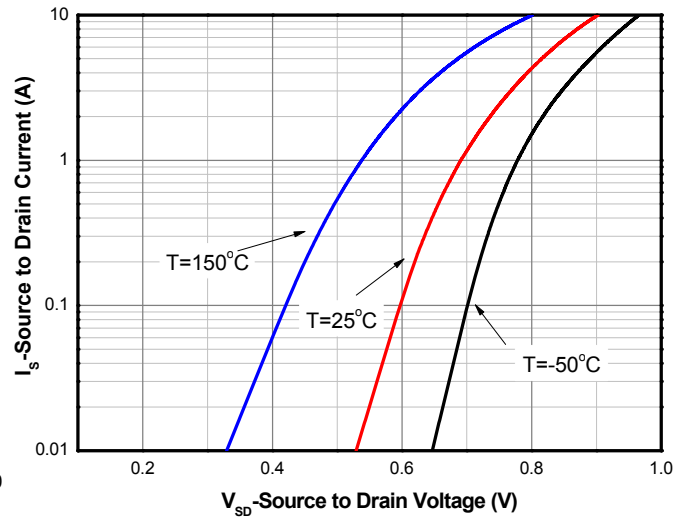
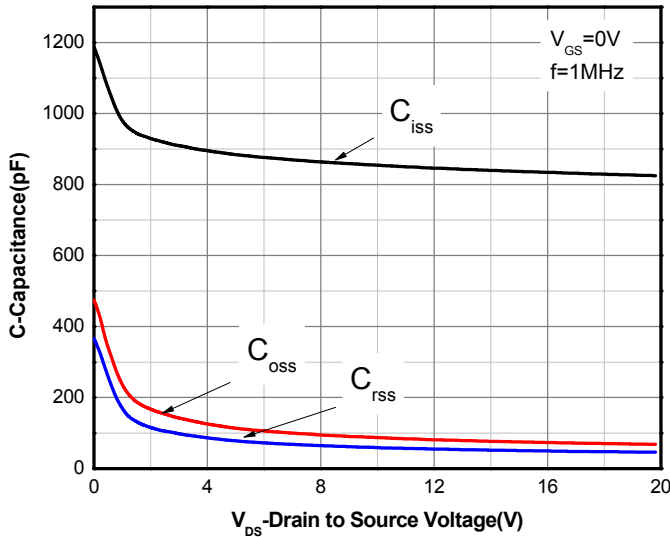
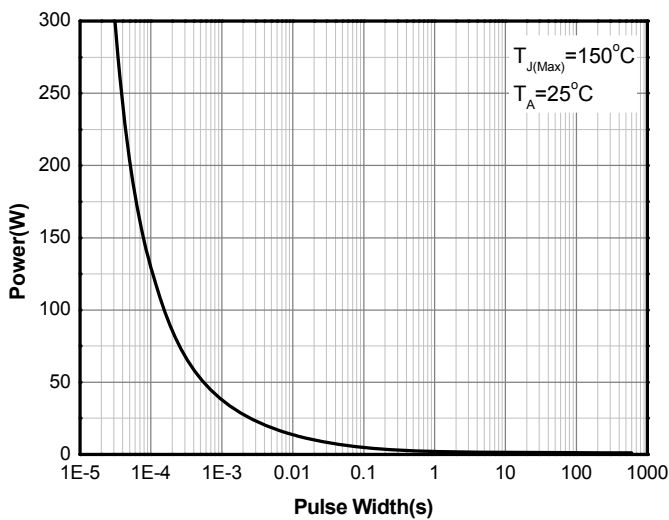
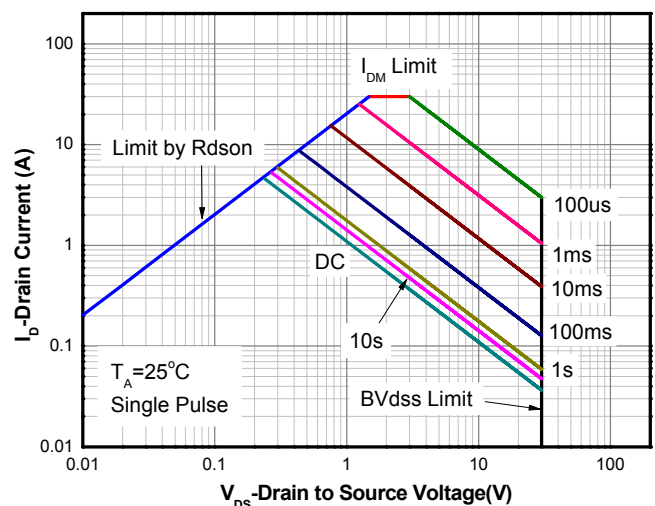
Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1-inch² (6.45cm²) with 2oz.(0.071mm thick) Copper pad on a 1.5*1.5 inch², 0.06-inch thick FR4 PCB, in a still air environment with $T_A = 25^{\circ}\text{C}$. The value in any given application is determined by the user's specific board design
- The power dissipation P_D is based on Junction-to-Ambient thermal resistance $R_{\theta JA}$ $t \leq 10\text{s}$ value and the $T_{J(\text{MAX})}=150^{\circ}\text{C}$.
- Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial $T_J = 25^{\circ}\text{C}$, the maximum allowed junction temperature of 150°C .
- The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

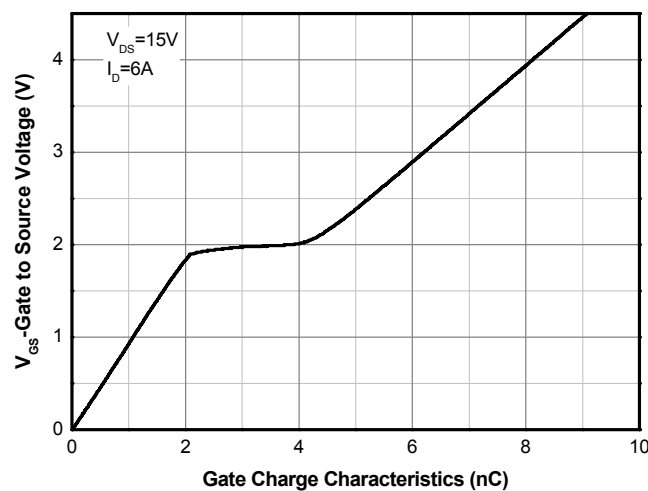
Electronics Characteristics (Ta=25°C, unless otherwise noted)

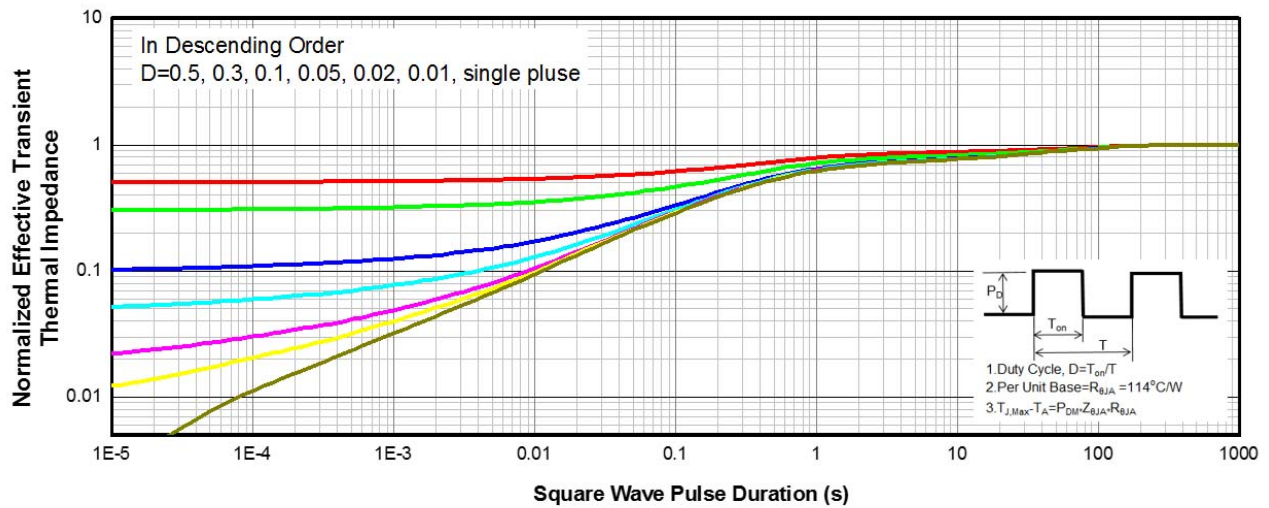
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0 V, I _D = 250uA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	uA
Gate-to-source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±10V			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250uA	0.7	1.0	1.5	V
Drain-to-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 6.0A		24	30	mΩ
		V _{GS} = 4.5V, I _D = 5.0A		25	31	
		V _{GS} = 3.1V, I _D = 3.5A		27	37	
		V _{GS} = 2.5V, I _D = 2.0A		29	44	
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0MHz, V _{DS} = 15 V		837		pF
Output Capacitance	C _{OSS}			75		
Reverse Transfer Capacitance	C _{RSS}			51		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 15 V, I _D = 6.0 A		9.1		nC
Threshold Gate Charge	Q _{G(TH)}			1.07		
Gate-to-Source Charge	Q _{GS}			1.83		
Gate-to-Drain Charge	Q _{GD}			2.17		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td(ON)	V _{GS} = 10 V, V _{DS} = 15 V, R _L =2.5Ω , R _G =3Ω		9.2		ns
Rise Time	tr			4.2		
Turn-Off Delay Time	td(OFF)			48.8		
Fall Time	tf			6.4		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V _{SD}	V _{GS} = 0 V, I _S = 1.0A		0.7	1.2	V

Typical Characteristics (Ta=25°C, unless otherwise noted)


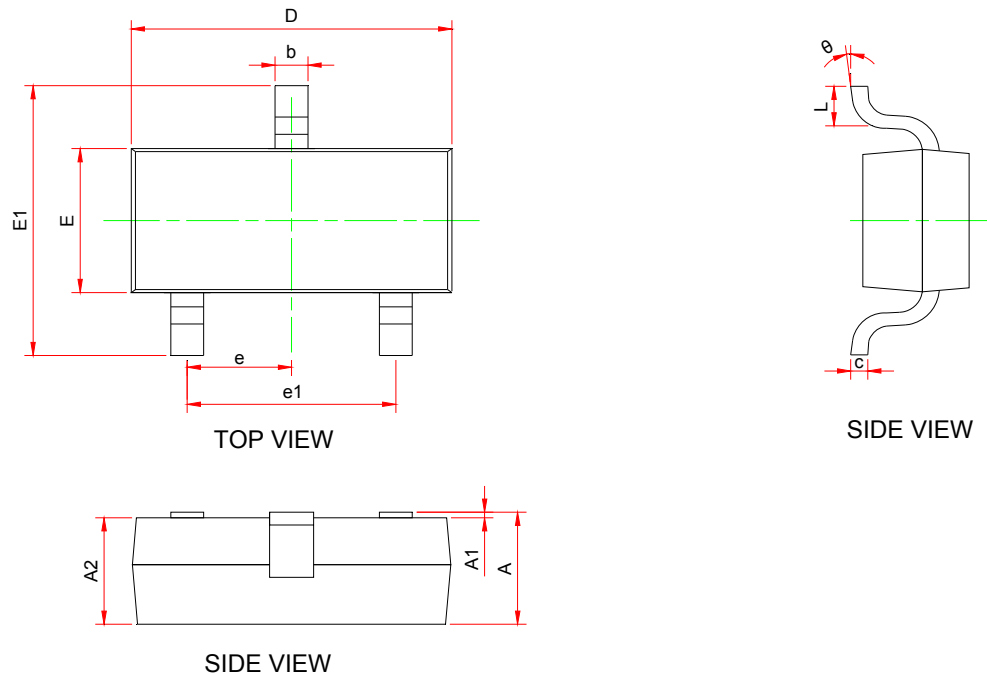

Capacitance

Single Pulse power
Body Diode Forward Voltage^d


* V_{GS} >minimum V_{GS} at which $R_{DS(ON)}$ is specified

Safe Operating Power

Gate Charge Characteristics



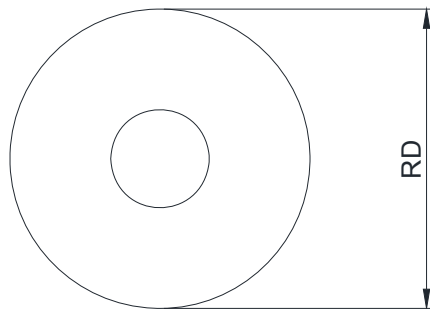
Transient thermal response (Junction-to-Ambient)

Package outline dimensions
SOT-23-3L


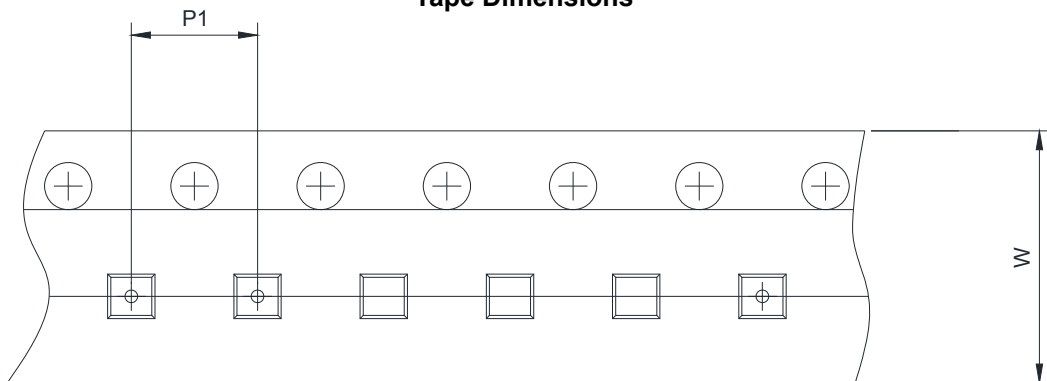
Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	-	-	1.25
A1	0.00	-	0.15
A2	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.10	-	0.20
D	2.82	2.92	3.03
E1	2.60	2.80	3.00
E	1.50	1.62	1.73
e	0.95 BSC		
e1	1.80	1.90	2.00
L	0.30	0.45	0.60
θ	0°	-	8°

TAPE AND REEL INFORMATION

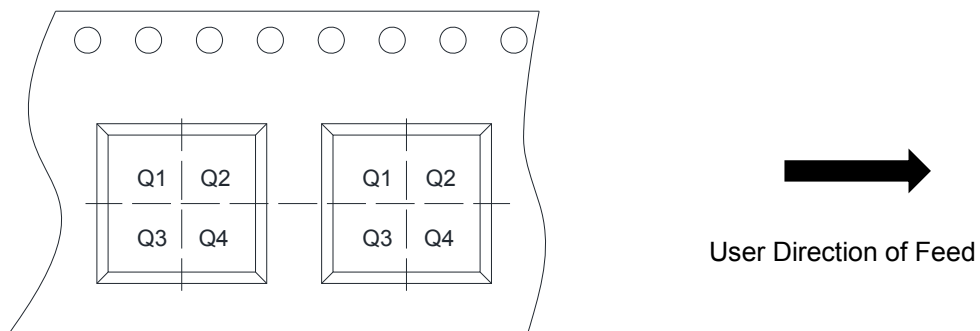
Reel Dimensions



Tape Dimensions



Quadrant Assignments For PIN1 Orientation In Tape



RD	Reel Dimension	☒ 7inch	☐ 13inch
W	Overall width of the carrier tape	☒ 8mm	☐ 12mm ☐ 16mm
P1	Pitch between successive cavity centers	☐ 2mm	☒ 4mm ☐ 8mm
Pin1	Pin1 Quadrant	☐ Q1	☐ Q2 ☒ Q3 ☐ Q4